ASSOCIATION CONNECTING LECTRONICS INDUSTRIES® ASSOCIATION CONNECTING LECTRONICS INDUSTRIES® international and Pan-Ame	annockburn, Illinois. A	ll rights reserved un ntions.	nder both Iev	nis docume vel parts, tl	ent is a declaration he declaration en	n of the substance compasses all low	es within the manufactur wer level materials for w	rer listed ite hich the ma	em. Note: if anufacturer	the item is an as has engineering	sembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
Supplier Information												
mpany name* Company unique ID			Uniq		Jnique ID Authority			Response Date*				
onsemi	emi							2023-06-08				
Contact Name	ame Title - Contact			1	Phone - Contact*				Email - Contact*			
Product-Env-Stewards	luct-Env-Stewards Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
athorized Representative* Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number N	Ifr Item Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		Veight*	UOM	Unit Type	
N	CP81381MNTXG Integrated Driver a		and MOSFET		2023-06-08 РНА		РНА	1	01.13	mg	Each	
Manufacturing Proccess Information					•			<u>,</u>				
Terminal Plating / Grid Array Material	rial Terminal Base Alloy		-STD-020 MSL R	ating	Peak Proce	Process Body Temperature Max Time at Peak		Temperature Number of Reflow Cycles			les	
Matte Tin (Sn) - annealed CU Alloy 3				260	С	30	second	ls 3				
Comments												
ATTENTION: MSL 3 Rated item requires Bake	e and Dry Pack (after	electrical test)										
for more information regarding material comp	osition please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et						
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company that agreement, will be the sole and exclusive	lease indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, admium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part compass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. ompany acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not dependently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the ertification in this paragraph. If the Company and the Supplier into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of at agreement, will be the sole and exclusivesource of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.									
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.02	mg	Supplier	Silicon (Si)	7440-21-3		3.02	mg
Die Attach Solder	5.35	mg	Supplier	Silver (Ag)	7440-22-4		0.1338	mg
			А	Lead (Pb)	7439-92-1	7a	4.9488	mg
			Supplier	Tin (Sn)	7440-31-5		0.2675	mg
Lead Frame	59.54	mg	Supplier	Silver (Ag)	7440-22-4		0.9824	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0714	mg
			Supplier	Iron (Fe)	7439-89-6		1.3992	mg
			Supplier	Copper (Cu)	7440-50-8		57.0691	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0179	mg
Mold Compound-Black	31.34	mg	Supplier	Epoxy resins	129915-35-1		1.567	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.567	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1254	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.7208	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		26.639	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.7208	mg
Plating	1.57	mg	Supplier	Tin (Sn)	7440-31-5		1.57	mg
Wire Bond - Au	0.31	mg	Supplier	Gold (Au)	7440-57-5		0.31	mg